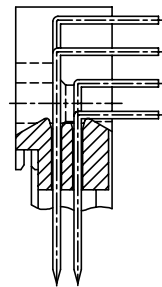
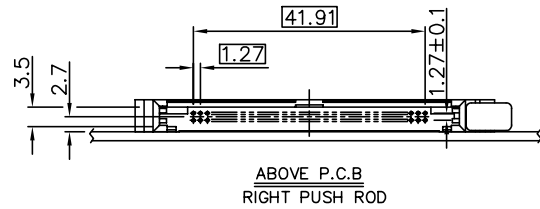
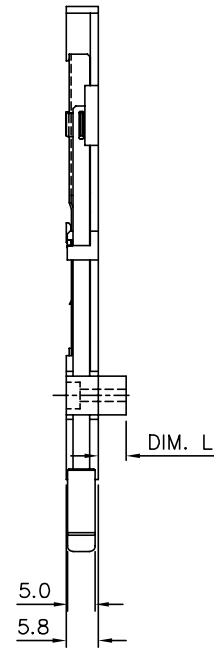
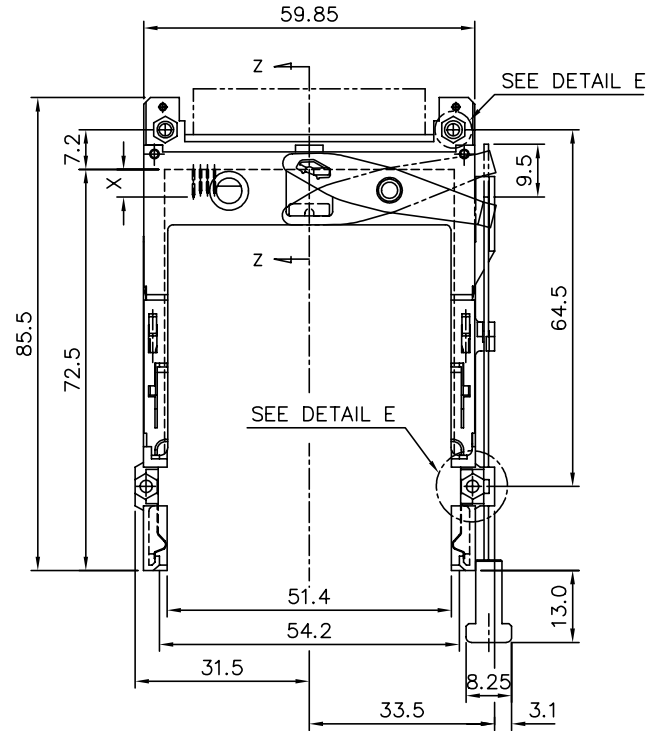
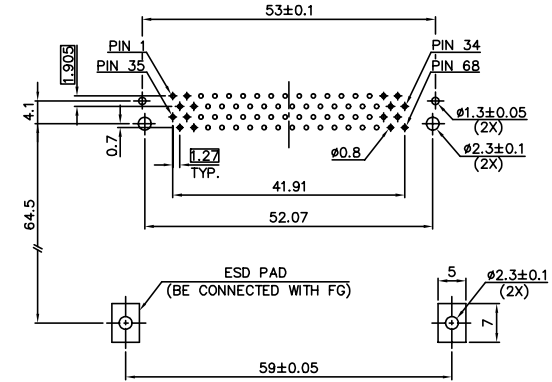


PRODUCT NO.	① PUSH ROD LOCATION	PCB SIDE	SOLDER TAIL	DIM. L STAND-OFF
10120632-000CALF	RIGHT	ABOVE	R/A	0



RIGHT ANGLE
 <SEC. Z-Z>



4 CARD INSERTION DIRECTION
 RECOMMENDED FOOT PRINT(MOUNTED SIDE)

NOTES:

- ① PUSH ROD LOCATION AND PCB SIDE ARE AS APPEARS INSTALLED.
2. MATERIAL
 - 2.1 HEADER ASS'Y:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY
 - 2.2 EJECT MECHANISM ASS'Y:
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE AND PUSH ROD : STAINLESS
EMI CONTACT: COPPER ALLOY
3. FINISH (PIN)
UNDER PLATING : 0.5µm MIN. Ni
CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni
SOLDER TAIL : 2.5µm MIN. PURE TIN
4. DIM "X"

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NO.	OTHERS	36,67	1,17,34,35,51,68
5. PRODUCT SPEC: 110-263
6. IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
7. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
8. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION

mat'l. code		surface / tolerance ASME Y14.5 / ASME Y14.5		projection / tolerance unless otherwise specified		product family PCMCIA	
l trechn nodr		date		angle		title	
A - ZK		04/13/12		±0.30		NARROW BODY EJ HEADER ASS'Y 68POS.	
				0°±2'		scale: 1.5:1	
		dr ZK HU 04/13/12		MM		dwg no	
		enr ZK HU 04/13/12		FCI		sheet 1 of 1 size	
		chr RICK BIAN 04/13/12				10120632 A4	
		appd RICK BIAN 04/13/12				type Product Customer Drawing	
sheet index	revision	A					
	sheet	1					